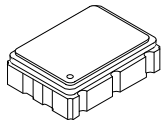


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

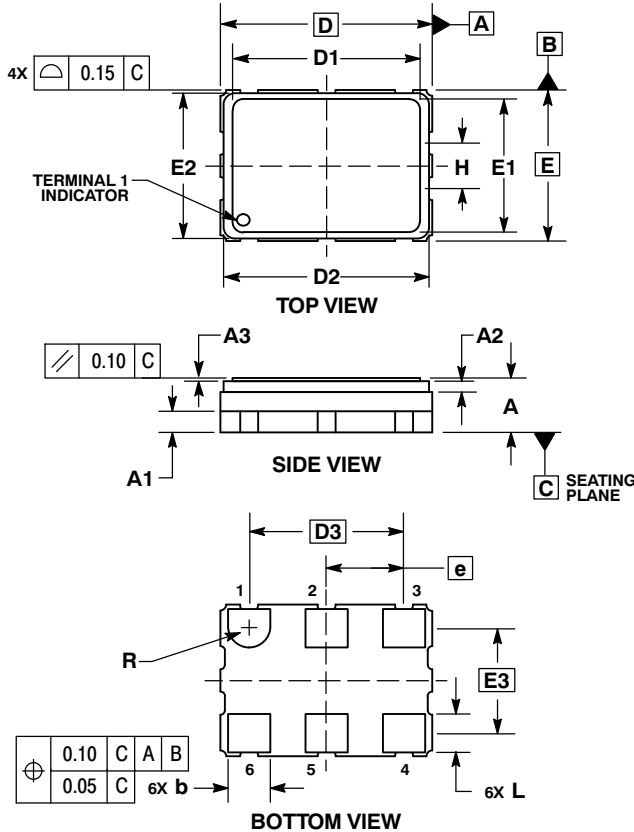
ON Semiconductor®



6 PIN CLCC, 7x5, 2.54P
CASE 848AB-01
ISSUE C

DATE 17 DEC 2007

SCALE 2:1

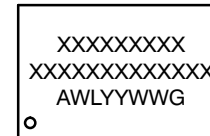


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.

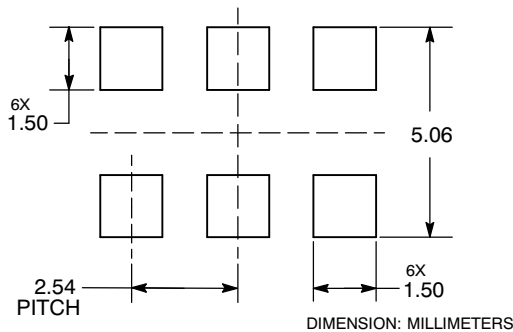
DIM	MILLIMETERS		
	MIN	NOM	MAX
A	1.70	1.80	1.90
A1	0.70 REF		
A2	0.36 REF		
A3	0.08	0.10	0.12
b	1.30	1.40	1.50
D	7.00 BSC		
D1	6.17	6.20	6.23
D2	6.66	6.81	6.96
D3	5.08 BSC		
E	5.00 BSC		
E1	4.37	4.40	4.43
E2	4.65	4.80	4.95
E3	3.49 BSC		
e	2.54 BSC		
H	1.80 REF		
L	1.17	1.27	1.37
R	0.70 REF		

GENERIC MARKING DIAGRAM*



- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

SOLDERING FOOTPRINT*



*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	6 PIN CLCC, 7X5, 2.54P	PAGE 1 OF 2

